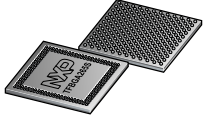


SOT1865-2

TFBGA265S, plastic thin fine-pitch ball grid array; 265 balls, 0.75 mm pitch, 13 mm x 13 mm x 1.04 mm body

2 July 2024

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA265S
Package type industry code	TFBGA265S
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-09-2017
Manufacturer package code	98ASA01108D

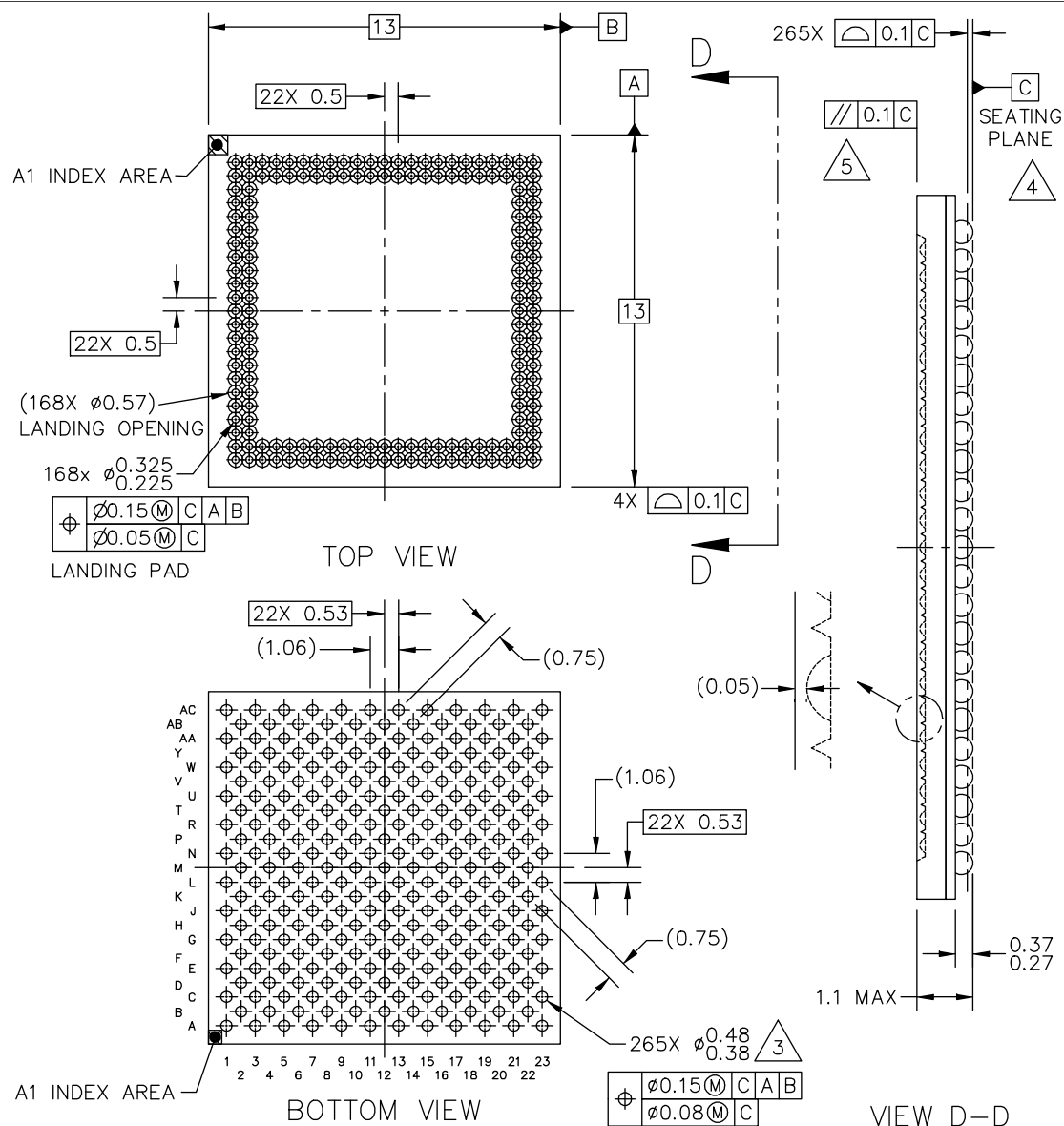
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	13	-	mm
package width	-	13	-	mm
seated height	-	1.04	-	mm
nominal pitch	-	0.75	-	mm
actual quantity of termination	-	265	-	



TFBGA265S, plastic thin fine-pitch ball grid array; 265 balls, 0.75 mm pitch, 13 mm x 13 mm x 1.04 mm body

2 Package outline



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TITLE: FLIP CHIP SIP STACKABLE, 13 X 13 X 1.04 PKG, (0.75)MM INTERSTITIAL PITCH, 265 I/O	DOCUMENT NO: 98ASA01108D	REV: 0
	STANDARD: NON-JEDEC	
	SOT1865-2	09 SEP 2017

Figure 1. Package outline TFBGA265S (SOT1865-2)

TFBGA265S, plastic thin fine-pitch ball grid array; 265 balls, 0.75 mm pitch, 13 mm x 13 mm x 1.04 mm body

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
 - 4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
 - 6. SCORING OR GROOVES ON TOP SURFACE OF PACKAGE IS NOT PERMITTED.
 - 7. NO VOIDS IN ENCAPSULATION PERMITTED.

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TITLE: FLIP CHIP SIP STACKABLE, 13 X 13 X 1.04 PKG, (0.75)MM INTERSTITIAL PITCH, 265 I/O	DOCUMENT NO: 98ASA01108D REV: 0	
	STANDARD: NON-JEDEC	
	SOT1865-2	09 SEP 2017

Figure 2. Package outline note TFBGA265S (SOT1865-2)

TFBGA265S, plastic thin fine-pitch ball grid array; 265 balls, 0.75 mm pitch, 13 mm x 13 mm x 1.04 mm body

3 Legal information

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TFBGA265S, plastic thin fine-pitch ball grid array; 265 balls, 0.75 mm pitch, 13 mm x 13 mm x 1.04 mm body

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